

Electronic Patent Application Fee Transmittal

Application Number:	10517670			
Filing Date:	13-Apr-2005			
Title of Invention:	Heat curable adhesive composition, article, semiconductor apparatus and method			
First Named Inventor/Applicant Name:	Kohichiro Kawate			
Filer:	John A. Burtis/Kathy Sandvig			
Attorney Docket Number:	58028US006			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 1 month with \$0 paid	1251	1	120	120

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Total in USD (\$)				120